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SIMULATION OF POLYMER FLOW DURING FUSED FILAMENT FABRICATION

INTRODUCTION

Unlike molding processes, additive manufacturing processes have few or no dedicated digital simulation tools. However, these tools are essential to predict the behavior of materials during their implementation and thus avoid tedious trial and error tests. In the case of FFF, several causes can lead to manufacturing failure. Among them, the risk of filament buckling or grinding can be important. Yet the occurrence of these phenomena is mostly dependent on the reaction force that the filament undergoes. Hence, the purpose of this study is to simulate the polymer flow in a FFF nozzle in order to predict the pressure drop and therefore the reaction load exerted on the filament at the hot end inlet.

MATERIALS AND METHODS

- System: the hot end of an A4v3 machine (cf. Figure 1) from the company 3ntr (Oleggio, Italy)
- Software: COMSOL Multiphysics®
- Geometry: geometry and boundary conditions provide a revolution symmetry,
- allowing to consider a 2D axi-symmetric model (cf. Figure 2). Material: PLA Ingeo™ 7000D from NatureWorks®

POLYMER FLOW

Polymer density was temperature dependent but not pressure dependent, resulting in a weakly compressible flow.

In all the polymer domains, the Navier-Stokes equations for laminar flow were solved:

:
$$\frac{\partial \rho}{\partial t} + \nabla \cdot (\rho \mathbf{u}) = 0$$

$$\rho \frac{\partial \mathbf{u}}{\partial t} + \rho (\mathbf{u} \cdot \nabla) \mathbf{u} = \nabla \cdot [-p\mathbf{I} + \mathbf{K}]$$

$$\mathbf{K} = \mu (\nabla \mathbf{u} + (\nabla \mathbf{u})^{\top}) - \frac{2}{2}\mu (\nabla \cdot \mathbf{u})\mathbf{I}$$

- p is the pressure (Pa) u is the velocity field (m.s-1) K is the deviatoric stress tensor I is the identity tensor (-)
- ρ is the density (kg.m⁻¹) μ is the dynamic viscosity (Pa.s)

Dynamic viscosity was shear-rate and temperature dependent, resulting in the choice of a Cross-WLF model:

y is the shear rate (s 1)

T is the temperature (K)

$$\mu(\hat{y}, T) = \frac{\mu_0(T)}{1 + \left(\mu_0(T) \frac{\hat{y}}{T^*}\right)^{1-n}}$$

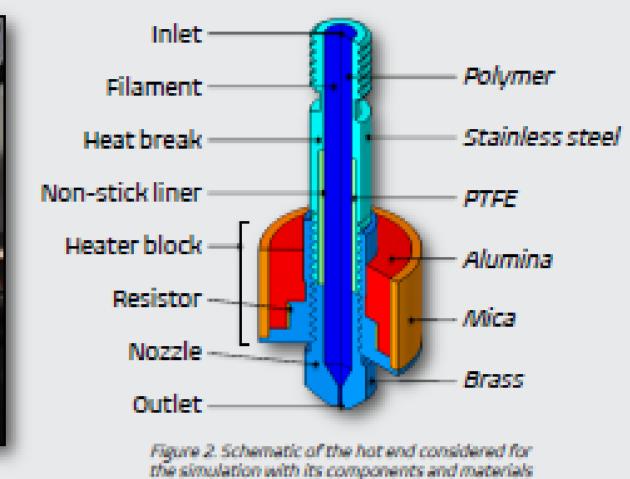
$$\mu_0(T) = D_1 \exp\left(-\frac{A_1(T - T^*)}{A_2 + (T - T^*)}\right)$$

 $\mu(\gamma,T) = \frac{\mu_0(T)}{1+\left(\mu_0(T)\frac{\dot{\gamma}}{\tau^*}\right)^{1-n}} \\ = \frac{\mu_0(T)}{1$

Boundary conditions:

- Slip condition (u · n = 0) between polymer and PTFE or stainless steel
- Non-slip condition (u = 0) between polymer and brass
- Velocity field at the inlet controlled by the solving sequence (cf. solver)
- Pressure at the outlet set to zero with no backflow allowed

Figure 1. Picture of the print head with its two hot ends inside the printer



CONDUCTIVE HEAT TRANSFER

Polymer thermal conductivity and heat capacity were temperature dependent, unlike the other materials. In all the hot end domains, the heat equation and Fourier's law were solved:

$$\rho \ C_p \frac{\partial T}{\partial t} + \rho \ C_p \ \mathbf{u} \cdot \nabla T + \nabla \cdot \mathbf{q} = Q \qquad \qquad \begin{array}{l} T \ \ \text{is the temperature (K)} \\ \mathbf{u} \ \ \text{is the velocity field (m.s-1)} \\ \mathbf{q} \ \ = -k \nabla T \qquad \qquad \mathbf{q} \ \ \text{is the heat flux density (W.} \end{array}$$

- q is the heat flux density (W.m.2) Q is the volumetric heat source (W.m-*)
- k is the thermal conductivity (W.m⁻¹.K⁻¹) ρ is the density (kg.m⁻ⁱ) C_p is the heat capacity (J.kg⁻¹.K⁻¹)

Boundary conditions:

- Convective heat flux $(\mathbf{n} \cdot \mathbf{q} = h(T T_{amb}))$ between external boundaries and air at $T_{amb} = 25$ °C.
- Conductance between the heat break and the heat sink (not represented)

Thin resistive layers between brass, stainless steel and alumina. Heat sources:

- Joule effect in the resistor: current intensity was controlled by a PID controller for which temperature was provided by a probe embedded in the alumina
 - Viscous dissipation within the polymer due to shear stress (Q_{vd} = K · ∇u)

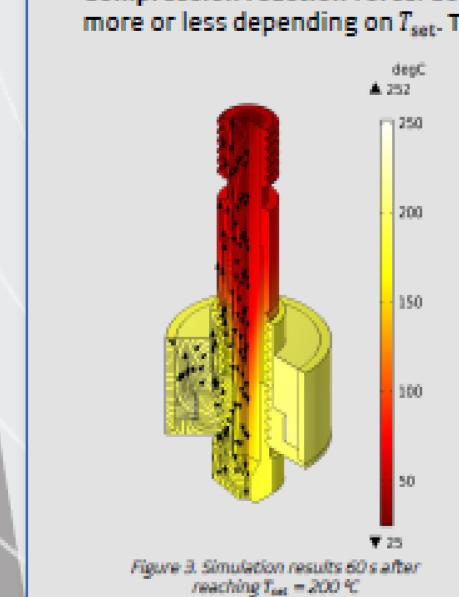
SOLVER

The time dependent simulations were carried out in 2 steps which used implicit, direct and fully coupled solvers:

- 1. The hot end was heated up from the uniform, ambient initial temperature. When the temperature at the tip of the PT100 probe approached the set temperature $(T_{\rm set} - T(t) < 1[K])$, a stop condition was activated for the solver, which triggered the second step
- 2. The PID controller kept the temperature constant at the tip of the PT100 probe and the filament was moved progressively from still to 1 mm.s⁻¹ over 2 s. The solver was stopped after 60 s.

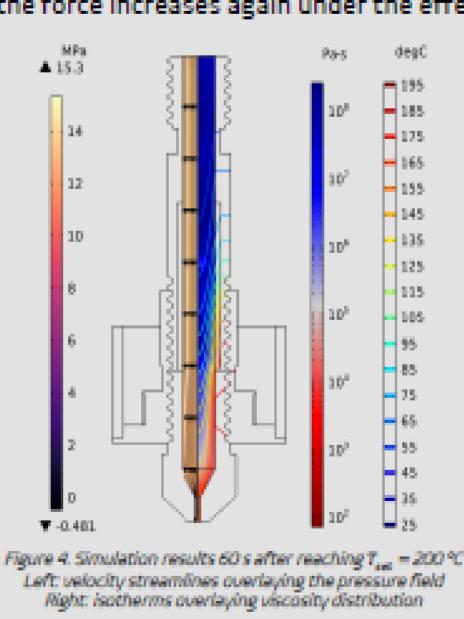
RESULTS

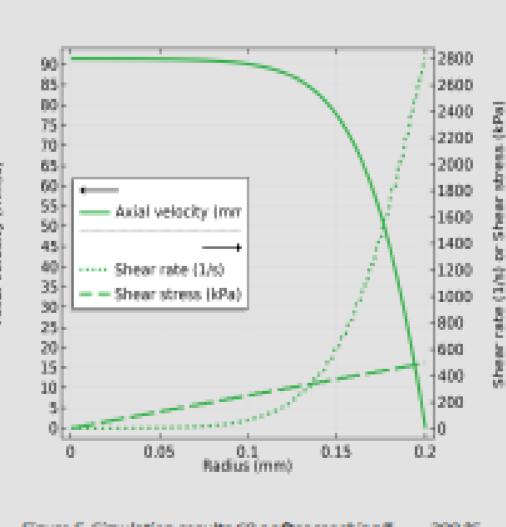
- Temperature gradients: important, as expected, in the axial direction, but also in the radial direction (cf. Figure 3).
- Pressure gradients: negligible in most of the hot end channel; the pressure drop responsible for the compression reaction force exerted on the incoming filament occurs mostly within the capillary (cf. Figure 4).
- Polymer within the capillary: at T_{set} = 200 °C and at mid-length of the capillary, the polymer velocity is uniform over a radius of 0.1 mm (cf. Figure 5). Shear rate reaches 2800 s⁻¹ on the capillary wall.
- Compression reaction force: decreases drastically with Tset (cf. Figure 6). Regardless of Tset, a peak is observed when the filament is set in motion, after which the force decreases more or less depending on T_{set}. Then the force increases again under the effect of the incoming colder polymer, before reaching a plateau corresponding to steady state.

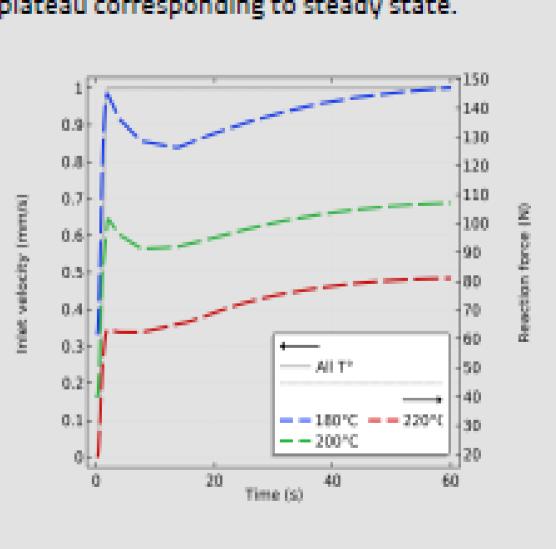


Heat flux density streamlines overlaying

the temperature field







rigure 6. Time dependent simulation results after reaching $T_{
m set}$

Filament velocity at the heat break inlet (left) and resulting

reaction force as a function of T ... (right)

Figure 5. Simulation results 60 s after reaching $T_{ext} = 200 \, ^{\circ}$ C. Avial velocity (left), shear rate and stress (right) at mid-length of the capillary channel along its radius

CONCLUSION

The influence of the nozzle temperature, filament velocity and shape of the nozzle on processing conditions can be assessed with this simulation. Though results are consistent with the expected orders of magnitude, measurements need to be carried out to adjust the model or its inputs, and eventually prove its reliability.

